

CASCADE

WATER-SOLUBLE SOLDER PASTE "CASCADE 1LF - C"



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CASCADE 1LF -C water-soluble solder paste is carefully formulated to confer high activity soldering. Its residues can be easily removed with deionised water.

- Halide-free
- Good water clean ability even after 24 hours
- Resistant to moisture ingress
- Long open time = 24h
- Long abandon time = 8 hours
- Very good tack-life = 16 hours
- Good slump resistance
- Long stencil-life = 8 hours
- Fine-pitch (400µm) and ultra-fine pitch (<300µm) capabilities in grade5

CASCADE 1LF-C water-soluble solder paste is made to strict quality assurance standards.

Alloy	Metal content (%)	Viscosity (Pa.s) J-STD 005
Sn96.5Ag3Cu0.5	88.5	143 +/-10%

Printing

Stencil

Stainless steel, brass or nickel. Chemical etched, laser cut or electroformed.

Squeegee

Stainless steel or 80-100 durometer polyurethane.

Print speed

20-80 mm/s. Generally slower for fine pitch.

Squeegee pressure

5-10 Kg. Generally higher for fine pitch.

Snap-off

0 to 0.25mm. On contact printing is preferred.

Ambient Conditions

21-26°C and 35% to 60% RH. Minimize exposure of paste direct to air flow.

Cleanup-Stencils and Tools

Water, water based cleaners.

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Reflow

Heating Methods

Convection, infrared, vapour phase, hot plate, hot bar, laser and others. Aerobic or inerted.

Heating Profile

See suggested reflow profile for specific alloy.

Cleaning

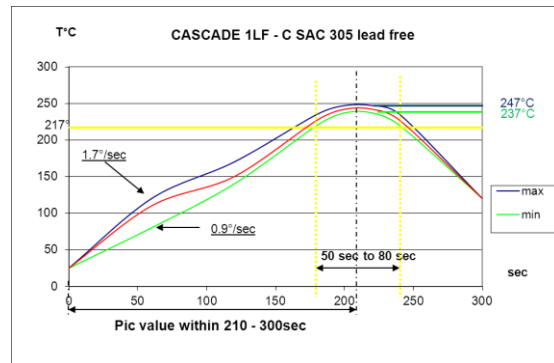
The post-soldered residue of **CASCADE LF™** is not particularly corrosive but is hygroscopic. Removal is necessary. This can be done by dishwasher, spray or immersion using cold or warm deionised water wash followed by rinsing with deionised water. Hot air dry.

Temperature

20-60°C.

Spray Pressure

20 to 40 psi.



Packaging: jars of 250g - other on request.

Storage: in original container between 2 and 10°C for up to 6 months. Wait until the pot has reached the ambient temperature before opening to avoid water condensation on the surface of the paste. Once opened, do not return to the fridge, then can be kept at ambient conditions for one week.

Additional information:

Our manufacturing processes have been subjected to FMECA analysis (equivalent of AMDEC in Europe).